

40V N-Channel Trench MOSFET(Preliminary)

General Description

- Trench Power technology
- Low R_{DS(ON)}
- Low Gate Charge
- Optimized for fast-switching applications

Applications

- Synchronous Rectification in DC/DC and AC/DC Converters
- Isolated DC/DC Converters in Telecom and Industrial

Product Summary

 V_{DS} 40V I_{D} (at V_{GS} =10V) 100A $R_{DS(ON)}$ (at V_{GS} =10V) < 4.5m Ω

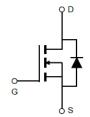
 $R_{DS(ON)}$ (at V_{GS} =4.5V) < 7.0m Ω

100% UIS Tested









Part Number	Package Type	Form	Marking
TTP100N04AT	TO-220	Tube	100N04AT

Absolute Maximum Ratings (T_A =25°C unless otherwise noted)

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V _{DS}	40	V
Gate-Source Voltage		V _{GS}	±20	V
Continuous Drain Correct B	T _C =25°C		100	•
Continuous Drain Current B	T _C =100°C	I _D	67	A
Pulsed Drain Current ^A		I _{DM}	300	А
Avalanche Current ^A Single Pulse Avalanche Energy L =0.3mH ^A		I _{AS}	24	А
		E _{AS}	86	mJ
Power Dissipation ^C	T _C =25°C	р	127	W
ower dissipation	T _C =100°C	P _D	78	W
Junction and Storage Temperature Range		T _J , T _{STG}	-55 to 175	°C

Thermal Characteristics

Parameter		Symbol	Maximum	Units	
Maximum Junction-to-Case	Steady-State	R _{⊕JC}	1.18	00.00	
Maximum Junction-to-Ambient	Steady-State	$R_{\Theta JA}$	100	°C/W	



Electric	cal Characteristics(T _J =25°C ur	nless otherwise	noted)				
0	Books	Conditions		Value			
Symbol	Parameter			Min	Тур	Max	Units
STATIC P	ARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	I _D =250μA,V _{GS} =0V		40			V
_			T _J =25°C			1	
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 40V, V_{GS} = 0V$	T _J =100°C			25	μA
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$,			±100	nA
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		1	1.7	2.4	V
D	Ctatia Duais Course On Besistance	V _{GS} =10V, I _D =30A			3.6	4.5	mΩ
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =4.5V, I _D =30A			5.3	7	mΩ
g _{FS}	Forward Transconductance	V _{DS} =10V, I _D =20A			22.1		S
V_{SD}	Diode Forward Voltage	I _S =30A, V _{GS} =0V				1	V
Is	Maximum Body-Diode Continuous Curre	rent ^B				100	Α
DYNAMIC	PARAMETERS				•		-
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =20V, f =1MH _Z			4484		
C _{oss}	Output Capacitance				831		pF
C _{rss}	Reverse Transfer Capacitance				386		
SWITCHIN	NG PARAMETERS						
Q _g (10V)	Total Gate Charge				80		
Q_{gs}	Gate Source Charge	V _{GS} =10V,V _{DS} =20V, I _D =50A			14		nC
Q_{gd}	Gate Drain Charge				14		
t _{D(on)}	Turn-On Delay Time	$V_{GS} = 10V, V_{DS} = 20V, I_{D} = 50A,$ $R_{G} = 3\Omega$			16		
t _r	Turn-On Rise Time				18		ns
$T_{D(off)}$	Turn-Off Delay Time				50		
t _f	Turn-Off Fall Time				22		
t _{rr}	Body Diode Reverse Recovery Time	1 200 4:/4+ 4000/			40		ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =20A, di/dt =100A/μs			44		nC

- A. Single pulse width limited by maximum junction temperature.
- B. The maximum current rating is package limited.
- C. The power dissipation P_D is based on $T_{J(MAX)} = 175$ °C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

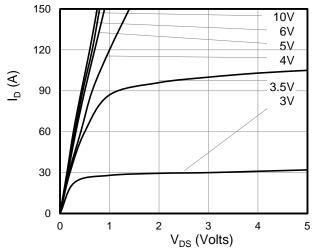


Figure 1: On-Region Characteristics

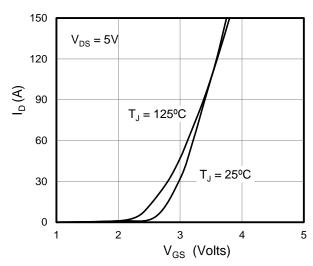


Figure 2: Transfer Characteristics

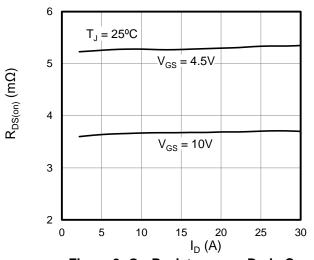


Figure 3: On-Resistance vs. Drain Current

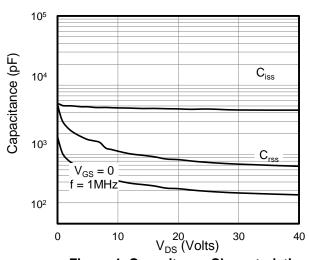


Figure 4: Capacitance Characteristics

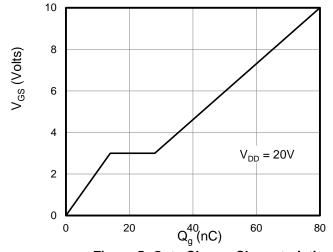


Figure 5: Gate Charge Characteristics

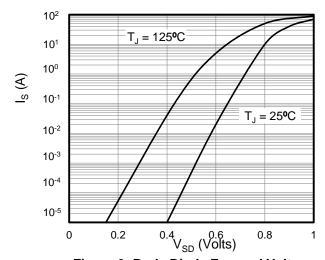


Figure 6: Body Diode Forward Voltage

 $Z_{\theta\,\text{JC}}$ Normalized Transient Thermal Resistance

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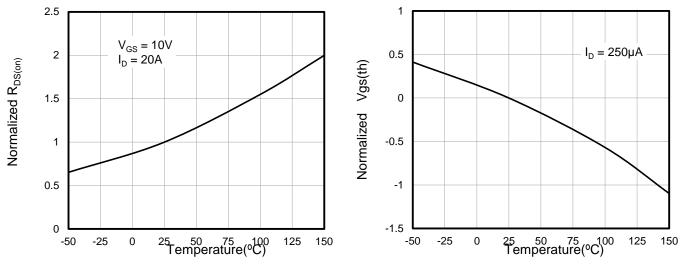
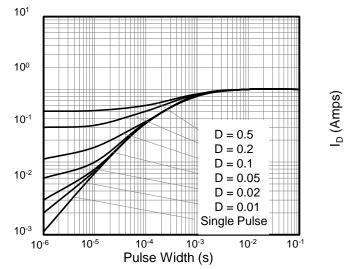


Figure 7: On-Resistance vs. Junction Temperature







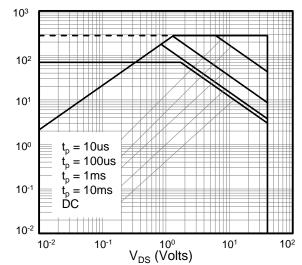


Figure 12: Safe Operating Area

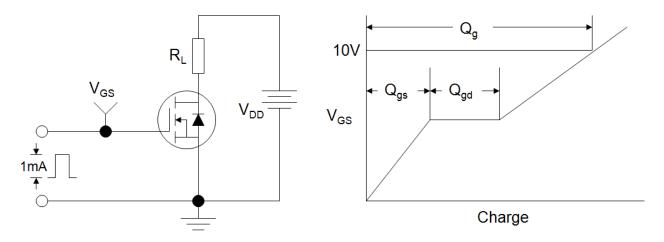


Figure A: Gate Charge Test Circuit and Waveforms

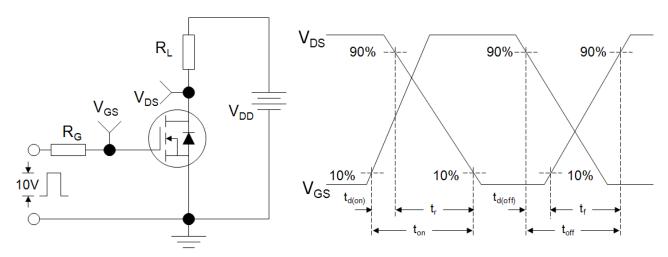


Figure B: Resistive Switching Test Circuit and Waveforms

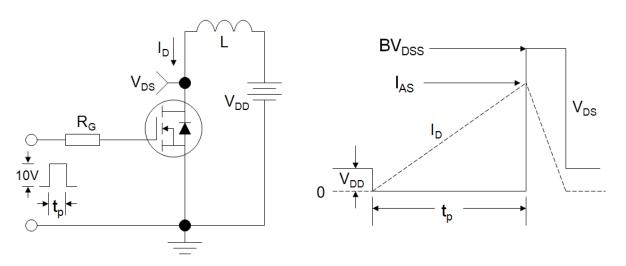
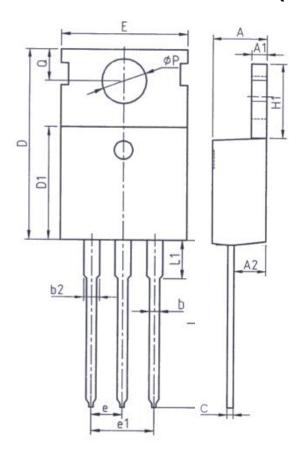
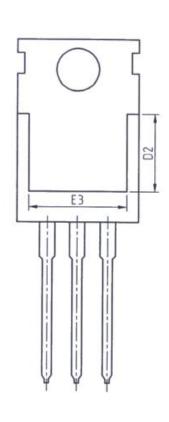


Figure C: Unclamped Inductive Switching (UIS) Test Circuit and Waveforms



TO-220(华天)



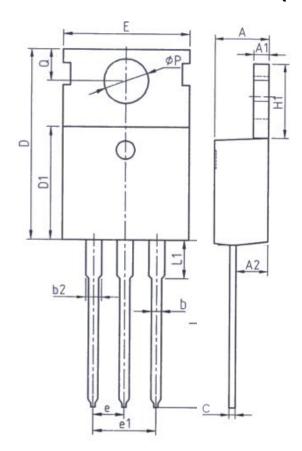


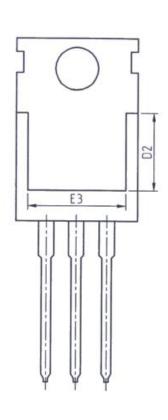
Unit: mm				
Symbol	Min.	Max.		
Α	4. 37	4. 77		
A1	1. 25	1. 45		
A2	2. 20	2. 60		
b	0. 70	0. 95		
b2	1. 17	1. 47		
С	0.40	0. 65		
D	15. 10	16. 10		
D1	8. 80	9. 40		
D2	5. 50	_		

Unit: mm				
Symbol	Min.	Max.		
E	9. 70	10. 30		
E3	7. 00	_		
е	2. 54BSC			
e1	5. 08BSC			
H1	6. 25	6. 85		
L	12. 75	13.80		
L1	-	3. 40		
P	3. 40	3. 80		
Q	2. 60	3. 00		



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Unit: mm			
Symbol	Min.	Max.	
Α	4. 37	4. 77	
A1	1. 25	1. 45	
A2	2. 20	2. 60	
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D2	5. 50	_	

Unit: mm				
Symbol	Min.	Max.		
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E3	7. 00	_		
е	2. 54BSC			
e1	5. 08BSC			
H1	6. 25	6. 85		
L	12. 75	13.80		
L1	_	3. 40		
Р	3. 40	3. 80		
Q	2. 60	3.00		



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